■Minimum Bus Cycle Time

- 83.3ns (12MHz) V_{DD}=2.8 to 5.5V
- 125ns (8MHz) V_{DD}=2.5 to 5.5V
- 500ns (2MHz) V_{DD}=2.2 to 5.5V

Note: The bus cycle time here refers to the ROM read speed.

■Minimum Instruction Cycle Time (tCYC)

- 250ns (12MHz) V_{DD}=2.8 to 5.5V
- 375ns (8MHz) V_{DD}=2.5 to 5.5V
- $1.5\mu s (2MHz)$ VDD=2.2 to 5.5V

■Ports

• Normal withstand voltage I/O ports

Ports whose I/O direction can be designated in 1-bit units 46 (P1n, P2n, P3n, P70 to P73, P80 to P86, PCn,

- Ports whose I/O direction can be designated in 4-bit units
- Normal withstand voltage input port
- Dedicated oscillator ports
- Reset pins
- Power pins

■Timers

- Timer 0: 16-bit timer/counter with a capture register
 - Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) ×2 channels
 - Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register)
 - + 8-bit counter (with an 8-bit capture register)
 - Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)
 - Mode 3: 16-bit counter (with a 16-bit capture register)
- Timer 1: 16-bit timer/counter that supports PWM/toggle outputs

Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs) + 8-bit timer/counter with an 8-bit prescaler (with toggle outputs)

Mode 1: 8-bit PWM with an 8-bit prescaler \times 2 channels

Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)

(toggle outputs also possible from the lower-order 8-bits)

Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs) (The lower-order 8 bits can be used as PWM)

- Timer 4: 8-bit timer with a 6-bit prescaler
- Timer 5: 8-bit timer with a 6-bit prescaler
- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Base timer
 - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
 - 2) Interrupts programmable in 5 different time schemes.

■High-speed Clock Counter

1) Can count clocks with a maximum clock rate of 24MHz (at a main clock of 12MHz)

2) Can generate output real-time.

■SIO

- SIO0: 8-bit synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Built-in 8-bit baudrate generator (maximum transfer clock cycle = 4/3 tCYC)
 - Automatic continuous data transmission (1 to 256 bits, specifiable in 1 bit units, suspension and resumption of data transmission possible in 1 byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
 - Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
 - Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
 - Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)

PWM2, PWM3, XT2) 8 (P0n) 1 (XT1) 2 (CF1, CF2)

- $2 (\underline{CF1}, \underline{CF2})$ 1 (RES)
- 6 (VSS1 to 3, VDD1 to 3)

■UART: 2 channels

- Full duplex
- 7/8/9 bit data bits selectable
- 1 stop bit (2 bit in continuous data transmission)
- Built-in baudrate generator (with baudrates of 16/3 to 8192/3 tCYC)

■AD Converter: 8 bits × 11 channels

■PWM: Multifrequency 12-bit PWM × 2 channels

Remote Control Receiver Circuit (sharing pins with P73, INT3, and T0IN)

- 1) Noise filtering function (noise filter time constant selectable from 1 tCYC, 32 tCYC, and 128 tCYC)
- 2) The noise filtering function is available for the INT3, T0IN, or T0HCP signal at P73. When P73 is read with an instruction, the signal level at that pin is read regardless of the availability of the noise filtering function.
- ■Watchdog Timer
 - External RC watchdog timer
 - Interrupt and reset signals selectable
- Clock Output Function

1) Able to output selected oscillation clock 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, 1/64 as system clock.

2) Able to output oscillation clock of sub clock.

■Interrupts

- 27 sources, 10 vector addresses
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
 - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source			
1	00003H	X or L	INTO			
2	0000BH	X or L	INT1			
3	00013H	H or L	INT2/T0L/INT4			
4	0001BH	H or L	INT3/INT5/base timer0/base timer1			
5	00023H	H or L	T0H/INT6			
6	0002BH	H or L	T1L/T1H/INT7			
7	00033H	H or L	SIO0/UART1 receive/UART2 receive			
8	0003BH	H or L	SIO1/UART1 transmit/UART2 transmit			
9	00043H	H or L	ADC/T6/T7			
10	0004BH	H or L	Port 0/T4/T5/PWM2, PWM3			

• Priority levels X > H > L

• Of interrupts of the same level, the one with the smallest vector address takes precedence.

Subroutine Stack Levels: 1024 levels (the stack is allocated in RAM)

■High-speed Multiplication/Division Instructions

- 16-bits \times 8-bits (5 tCYC execution time)
- 24-bits \times 16-bits (12 tCYC execution time)
- 16-bits ÷ 8-bits (8 tCYC execution time)
- 24-bits ÷ 16-bits (12 tCYC execution time)

■Oscillation Circuits

- RC oscillation circuit (internal)
- CF oscillation circuit
- Crystal oscillation circuit

- : For system clock
- : For system clock, with internal Rf
- cuit : For low-speed system clock
- Multifrequency RC oscillation circuit (internal) : For system clock

■System Clock Divider Function

- Can run on low current.
- The minimum instruction cycle selectable from 250ns, 500ns, 1.0µs, 2.0µs, 4.0µs, 8.0µs, 16.0µs, 32.0µs, and 64.0µs (at a main clock rate of 12MHz).

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
 - 1) Oscillation is not halted automatically.
 - 2) Canceled by a system reset or occurrence of an interrupt.
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
 - 1) The CF, RC, and crystal oscillators automatically stop operation.
 - 2) There are three ways of resetting the HOLD mode.
 - (1) Setting the reset pin to the lower level.
 - (2) Setting at least one of the INTO, INT1, INT2, INT4, and INT5 pins to the specified level
 - (3) Having an interrupt source established at port 0
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer.
 - 1) The CF and RC oscillators automatically stop operation.
 - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
 - 3) There are four ways of resetting the X'tal HOLD mode.
 - (1) Setting the reset pin to the low level
 - (2) Setting at least one of the INTO, INT1, INT2, INT4, and INT5 pins to the specified level
 - (3) Having an interrupt source established at port 0
 - (4) Having an interrupt source established in the base timer circuit

■On-chip Debugger Function

• Permits software debugging with the test device installed on the target board.

■Development Tools

- Evaluation (EVA) chip : LC87EV690
- Emulator
 - : EVA62S + ECB876600D + SUB875M00 + POD64QFP ICE-B877300 + SUB875M00 + POD64QFP
- On-chip-debugger

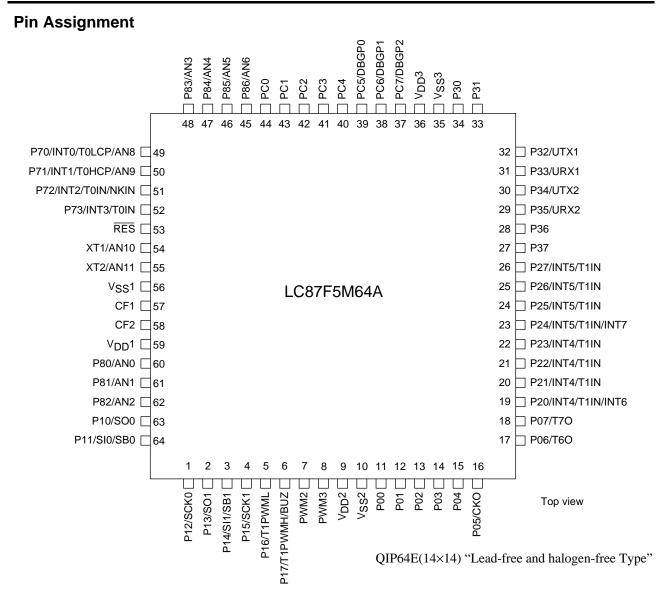
: TCB87-TypeB + LC87F5M64A

Programming Boards

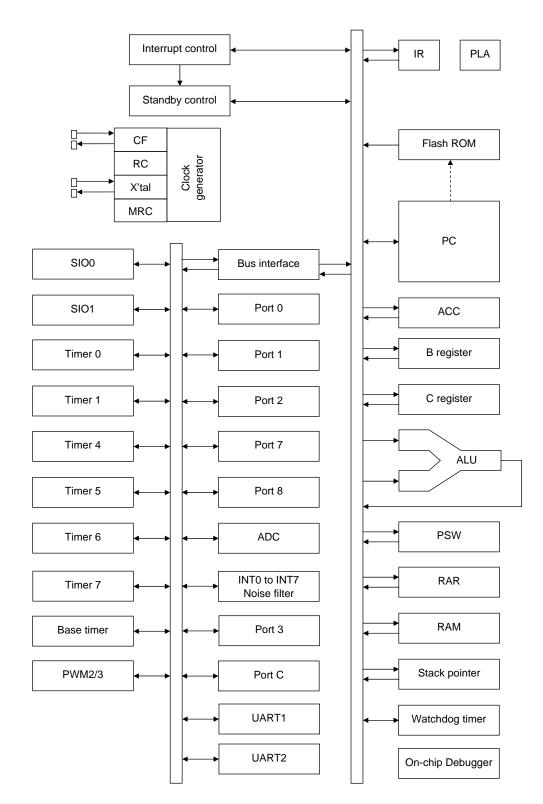
Package	Programming boards
QIP64E(14 × 14)	W87F50256Q

■Flash ROM Programmer

Maker	Model	Support version(Note)	Device		
Flash Support Group, Inc.(Single)	AF9708/09/09B (including product of Ando Electric Co.,Ltd)	Revision : After Rev.02.73	LC87F6D64A		
Flash Support	AF9723(Main body) (including product of Ando Electric Co.,Ltd)	Revision : After Rev.02.29	LC87F5M64A		
Group, Inc.(Gang)	AF9833(Unit) (including product of Ando Electric Co.,Ltd)	Revision : After Rev.01.88	LC87F5M64A		
Our company	SKK/SKK Type-B/SKK DBG Type-B (SANYO FWS)	Application Version: After 1.04 Chip Data Version: After2.10	LC87F5M64A		



System Block Diagram



Pin Description

Pin Name	I/O			Des	scription			Option	
V _{SS} 1, V _{SS} 2 V _{SS} 3	-	- Power supply p	in					No	
V _{DD} 1, V _{DD} 2 V _{DD} 3	-	+ Power supply p	bin					No	
Port 0	I/O	• 8-bit I/O port						Yes	
P00 to P07		• I/O specifiable	n 4-bit units						
		 Pull-up resistor 	can be turned	on and off in 4-b	it units				
		HOLD release	nput						
		Port 0 interrupt	input						
	Shared Pins								
	P05: Clock output (system clock/can selected from sub clock)								
P06: Timer 6 toggle output									
		P07: Timer 7 to	ggle output						
Port 1	I/O	 8-bit I/O port 						Yes	
P10 to P17 • I/O specifiable in 1-bit units									
		 Pull-up resistor 	can be turned	on and off in 1-b	it units				
		 Pin functions 							
		P10: SIO0 data	output						
		P11: SIO0 data	input/bus I/O						
		P12: SIO0 cloc	k I/O						
		P13: SIO1 data	output						
		P14: SIO1 data	input/bus I/O						
		P15: SIO1 cloc	k I/O						
		P16: Timer 1 P	WML output						
		P17: Timer 1 P	WMH output/be	eper output					
Port 2	I/O	 8-bit I/O port 						Yes	
P20 to P27			I/O specifiable in 1-bit units						
		 Pull-up resistor 	can be turned	on and off in 1-b	it units				
		Other functions							
		P20: INT4 inpu	t/HOLD reset in	put/timer 1 even	t input/timer 0L o	capture input/			
				-	L capture 1 input				
			-	reset input/timer	1 event input/tin	ner 0L capture ir	nput/		
		timer 0H o	capture input						
				•	t input/timer 0L o	• •			
				•	H capture 1 inpu				
			-	reset input/timer	1 event input/tin	ner 0L capture ir	nput/		
	timer 0H capture input								
		 Interrupt ackno 	wledge type		1	1	· · · · · ·		
			Rising	Falling	Rising/ Falling	H level	L level		
		INT4	enable	enable	enable	disable	disable		
	1	INT5	enable	enable	enable	disable	disable		
		INT6	enable	enable	enable	disable	disable		

Continued on next page.

Pin Name	I/O			Des	cription			Option	
Port 7	I/O	• 4-bit I/O port						No	
P70 to P73		I/O specifiable i	n 1-bit units						
		Pull-up resistor can be turned on and off in 1-bit units							
		Shared Pins							
		P70: INT0 input/HOLD reset input/timer 0L capture input/watchdog timer output P71: INT1 input/HOLD reset input/timer 0H capture input P72: INT2 input/HOLD reset input/timer 0 event input/timer 0L capture input/							
		high speed clock counter input							
		P73: INT3 input (with noise filter)/timer 0 event input/timer 0H capture input							
		AD converter in	put port: AN8 (I	P70), AN9 (P71)					
	Interrupt acknowledge type								
			Rising	Falling	Rising/	H level	L level		
			Trising	i anng	Falling	THEVE	Elever		
		INT0	enable	enable	disable	enable	enable		
		INT1	enable	enable	disable	enable	enable		
		INT2	enable	enable	enable	disable	disable		
		INT3	enable	enable	enable	disable	disable		
Port 8	I/O	• 7-bit I/O port						No	
P80 to P86		• I/O specifiable in 1-bit units							
		 Shared Pins 							
		AD converter in	put port : AN0 ((P80) to AN6 (P8	6)				
PWM2	I/O	PWM2 and PW	M3 output ports	5				No	
PWM3		General-purpos	e I/O available						
Port 3	I/O	 8-bit I/O port 						Yes	
P30 to P37		 I/O specifiable i 	n 1-bit units						
		Pull-up resistor can be turned on and off in 1-bit units							
		Pin functions							
		P32: UART1 transmit							
		P33: UART1 receive							
		P34: UART2 transmit							
		P35: UART2 red	ceive						
Port C	I/O	• 8-bit I/O port						Yes	
PC0 to PC7		I/O specifiable in							
		Pull-up resistor	can be turned o	on and off in 1-bi	tunits				
		Pin functions							
<u> </u>	1		P2(PC5 to PC7	'): On-chip Debu	gger				
RES	Input	Reset pin						No	
XT1	Input	• 32.768kHz crys	tal oscillator inp	out pin				No	
		 Shared pins 							
		General-purpos							
		AD converter in							
		Must be connec	ted to V _{DD} 1 if	not to be used.					
XT2	I/O	• 32.768kHz crys	tal oscillator inp	out pin				No	
		 Shared pins 							
		General-purpos							
		AD converter in	-						
		Must be set for oscillation and kept open if not to be used.							
CF1	Input	Ceramic resonate	or input pin					No	
CF2	Output	Ceramic resonate	or output pin					No	

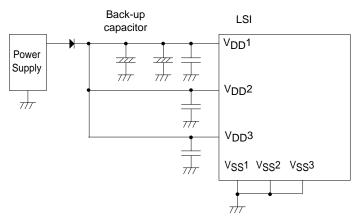
Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor. Data can be read into any input port even if it is in the output mode.

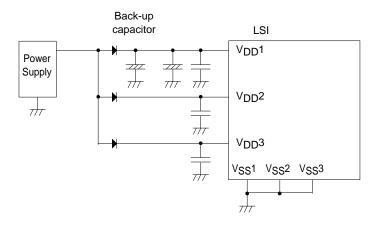
Port Name	Options Selected in Units of	Option Type	Output Type	Pull-up Resistor
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	No
P10 to P17	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P20 to P27	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable
P71 to P73	-	No	CMOS	Programmable
P80 to P86	-	No	Nch-open drain	No
PWM2, PWM3	-	No	CMOS	No
P30 to P37	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
PC0 to PC7	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
XT1	-	No	Input for 32.768kHz crystal oscillator (Input only)	No
XT2	-	No	Output for 32.768kHz crystal oscillator (Nch-open drain when in general-purpose output mode)	No

Note 1: Programmable pull-up resistors for port 0 are controlled in 4-bit units (P00 to 03, P04 to 07).

⁽Example 1) When backup is active in the HOLD mode, the high level of the port outputs is supplied by the backup capacitors.



(Example 2) The high-level output at the ports is unstable when the HOLD mode backup is in effect.



^{*1:} Make the following connection to minimize the noise input to the V_{DD}1 pin and prolong the backup time. Be sure to electrically short the V_{SS}1, V_{SS}2, and V_{SS}3 pins.

	Parameter	Symbol	Pins/Remarks	Conditions		r	Spec	ification	
	. aramotor				V _{DD} [V]	min	typ	max	uni
	ximum supply age	V _{DD} max	V _{DD} 1, V _{DD} 2, V _{DD} 3	V _{DD} 1=V _{DD} 2=V _{DD} 3		-0.3		+6.5	
np	ut voltage	V _I (1)	XT1, CF1			-0.3		V _{DD} +0.3	
np	ut/Output voltage	V _{IO} (1)	Ports 0, 1, 2 Ports 7, 8 Ports 3, C PWM2, PWM3, XT2			-0.3		V _{DD} +0.3	V
	Peak output current	IOPH(1)	Ports 0, 1, 2 Ports 3, C	CMOS output select Per 1 application pin		-10			
		IOPH(2)	PWM2, PWM3	Per 1 application pin.		-20			
		IOPH(3)	P71 to P73	Per 1 application pin.		-5			
÷	Mean output current	IOMH(1)	Ports 0, 1, 2 Ports 3, C	CMOS output select Per 1 application pin		-7.5			
rrent	(Note1-1)	IOMH(2)	PWM2, PWM3	Per 1 application pin		-10			
it cui	. ,	IOMH(3)	P71 to P73	Per 1 application pin		-3			
utpr	Total output	ΣIOAH(1)	P71 to P73	Total of all applicable pins		-10			
High level output current	current	ΣIOAH(2)	Ports, 1 PWM2, PWM3	Total of all applicable pins		-25			
Higt		ΣIOAH(3)	Ports 0, 2	Total of all applicable pins		-25			
		ΣIOAH(4)	Ports 0, 1, 2 PWM2, PWM3	Total of all applicable pins		-45			
		ΣIOAH(5)	Port 3	Total of all applicable pins		-25			
		ΣIOAH(6)	Ports C	Total of all applicable pins		-25			
		ΣIOAH(7)	Ports 3, C	Total of all applicable pins		-45			
	Peak output	IOPL(1)	P02 to P07	Per 1 application pin		-			
	current		Ports 1, 2 Ports 3, C PWM2, PWM3					20	m
		IOPL(2)	P00, P01	Per 1 application pin				30	
		IOPL(3)	Ports 7, 8, XT2	Per 1 application pin				10	
nt	Mean output current (Note1-1)	IOML(1)	P02 to P07 Ports 1, 2 Ports 3, C PWM2, PWM3	Per 1 application pin				15	
urre		IOML(2)	P00, P01	Per 1 application pin				20	
put c		IOML(3)	Ports 7, 8, XT2	Per 1 application pin				7.5	
Low level output current	Total output current	ΣIOAL(1)	Port 7 P83 to P86, XT2	Total of all applicable pins				15	
e ve		ΣIOAL(2)	P80 to P82	Total of all applicable pins				15	
Ľ		ΣIOAL(3)	Ports 7, 8, XT2	Total of all applicable pins				20	
		ΣIOAL(4)	Ports 1 PWM2, PWM3	Total of all applicable pins				45	
		ΣIOAL(5)	Ports 0, 2	Total of all applicable pins				45	
		ΣIOAL(6)	Ports 0, 1, 2 PWM2, PWM3	Total of all applicable pins				80	
		ΣIOAL(7)	Port 3	Total of all applicable pins				45	
		ΣIOAL(8)	Ports C	Total of all applicable pins				45	
		ΣIOAL(9)	Ports 3, C	Total of all applicable pins				80	
	ximum power sipation	Pd max	QIP64E(14×14)	Ta=-40 to +85°C				300	۳۱
	erating ambient nperature	Topr				-40		+85	°(
Sto	rage ambient	Tstg	1		1				

Absolute Maximum Ratings at $Ta = 25^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Note 1-1: The mean output current is a mean value measured over 100ms.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

	Ourseland.	Dive (Derseeler	Quanditiana			Specif	ication		
arameter	Symbol	Pins/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
rating	V _{DD} (1)	V _{DD} 1=V _{DD} 2=V _{DD} 3	0.245µs≤ tCYC≤200µs		2.8		5.5		
oly voltage			0.367µs≤ tCYC≤200µs		2.5		5.5		
e2-1)			1.47μs≤ tCYC≤200μs		2.2		5.5		
nory aining bly voltage	VHD	V _{DD} 1=V _{DD} 2=V _{DD} 3	RAM and register contents sustained in HOLD mode		2.0		5.5		
n level input age	∨ _{IH} (1)	Ports 1, 2 P71 to P73 P70 port input/ interrupt side		2.2 to 5.5	0.3V _{DD} +0.7		V _{DD}		
	V _{IH} (2)	Ports 0, 8, 3, C PWM2, PWM3		2.2 to 5.5	0.3V _{DD} +0.7		V _{DD}		
	V _{IH} (3)	P70 watchdog timer side		2.2 to 5.5	0.9V _{DD}		V _{DD}	V	
	V _{IH} (4)	XT1, XT2, CF1, RES		2.2 to 5.5	0.75V _{DD}		V _{DD}		
level input age	V _{IL} (1)	Ports 1, 2 P71 to P73		4.0 to 5.5	V _{SS}		0.1V _{DD} +0.4		
		P70 port input/ Interrupt side		2.2 to 4.0	V _{SS}		0.2V _{DD}		
	V _{IL} (2)	Ports 0, 8, 3, C PWM2, PWM3		4.0 to 5.5	V _{SS}		0.15V _{DD} +0.4		
				2.2 to 4.0	VSS		0.2V _{DD}		
	V _{IL} (3)	Port 70 watchdog timer side		2.2 to 5.5	V _{SS}		0.8V _{DD} -1.0		
	V _{IL} (4)	XT1, XT2, CF1, RES		2.2 to 5.5	VSS		0.25V _{DD}		
ruction cycle	tCYC			2.8 to 5.5	0.245		200		
				2.5 to 5.5	0.367		200	μs	
e2-2)				2.2 to 5.5	1.47		200		
ernal system	FEXCF(1)	CF1	CF2 pin open	2.8 to 5.5	0.1		12		
k frequency			System clock frequency	2.5 to 5.5	0.1		8		
			 division rate=1/1 External system clock duty=50±5% 	2.2 to 5.5	0.1		2	MHz	
			CF2 pin open	2.8 to 5.5	0.2		24.4		
			System clock frequency	2.5 to 5.5	0.1		16		
			division rate=1/2	2.2 to 5.5	0.1		4		
illation uency	FmCF(1)	CF1, CF2	12MHz ceramic oscillation See Fig. 1.	2.8 to 5.5		12			
ie e2-3)	FmCF(2)	CF1, CF2	8MHz ceramic oscillation See Fig. 1.	2.5 to 5.5		8			
	FmCF(3)	CF1, CF2	4MHz ceramic oscillation See Fig. 1.	2.2 to 5.5		4		MHz	
	FmRC		Internal RC oscillation	2.2 to 5.5	0.3	1.0	2.0		
	FmMRC		Frequency variable RC oscillation	2.5 to 5.5		16			
Ē	FsX'tal	XT1, XT2	32.768kHz crystal oscillation See Fig. 2.	2.2 to 5.5		32.768		kHz	
uency Je	FmCF(2) FmCF(3) FmRC FmMRC	CF1, CF2 CF1, CF2	See Fig. 1. 8MHz ceramic oscillation See Fig. 1. 4MHz ceramic oscillation See Fig. 1. Internal RC oscillation Frequency variable RC oscillation source oscillation 32.768kHz crystal oscillation	2.8 to 5.5 2.5 to 5.5 2.2 to 5.5 2.2 to 5.5 2.5 to 5.5		8 4 1.0 16			

Allowable Operating Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Note 2-1: V_{DD} must be held greater than or equal to 2.7V in the flash ROM onboard programming mode.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Electrical Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, V	$V_{SS1} = V_{SS2} = V_{SS3} = 0V$
--	------------------------------------

Parameter	Symbol	Pins/Remarks	Conditions	-		Specific	ation	
Falameter	Symbol	Fills/Itelliaiks	Conditions	V _{DD} [V]	min	typ	max	unit
High level input current	I _{IH} (1)	Ports 0, 1, 2 Ports 7, 8 Ports 3, C RES PWM2, PWM3	Output disabled Pull-up resistor off V _{IN} =V _{DD} (Including output Tr's off leakage current))	2.2 to 5.5			1	
	I _{IH} (2)	XT1, XT2	For input port specification VIN=VDD	2.2 to 5.5			1	
	I _{IH} (3)	CF1	V _{IN} =V _{DD}	2.2 to 5.5			15	
Low level input current	I _{IL} (1)	Ports 0, 1, 2 Ports 7, 8 Ports 3, C RES PWM2, PWM3	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current))	2.2 to 5.5	-1			μA
	I _{IL} (2)	XT1, XT2	For input port specification VIN=VSS	2.2 to 5.5	-1			
	I _{IL} (3)	CF1	V _{IN} =V _{SS}	2.2 to 5.5	-15			
High level output	V _{OH} (1)	Ports 0, 1, 2	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)	Ports 3, C	I _{OH} =-0.4mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (3)		I _{OH} =-0.2mA	2.2 to 5.5	V _{DD} -0.4			
	V _{OH} (4)	Ports 71 to 73	I _{OH} =-0.4mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (5)	-	I _{OH} =-0.2mA	2.2 to 5.5	V _{DD} -0.4			
	V _{OH} (6)	PWM2, PWM3	I _{OH} =-10mA	4.5 to 5.5	V _{DD} -1.5			
	V _{OH} (7)		I _{OH} =-1.6mA	3.0 to 5.5	V _{DD} -0.4			v
	V _{OH} (8)		I _{OH} =-1mA	2.2 to 5.5	V _{DD} -0.4			
Low level output	V _{OL} (1)	Ports 0, 1, 2	I _{OL} =10mA	4.5 to 5.5			1.5	
voltage	V _{OL} (2)	Ports 3, C	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (3)	PWM2, PWM3,	I _{OL} =1mA	2.2 to 5.5			0.4	
	V _{OL} (4)	Ports 7, 8	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (5)	XT2	I _{OL} =1mA	2.2 to 5.5			0.4	
	V _{OL} (6)	P00, P01	I _{OL} =30mA	4.5 to 5.5			1.5	
	V _{OL} (7)		I _{OL} =5mA	3.0 to 5.5			0.4	
	V _{OL} (8)		I _{OL} =2.5mA	2.2 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 7	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	35	80	
	Rpu(2)	Ports 3, C		2.2 to 5.5	18	35	150	kΩ
Hysteresis voltage	VHYS	RES Ports 1, 2, 7		2.2to 5.5		0.1V _{DD}		V
Pin capacitance	CP	All pins	 For pins other than that under test: V_{IN}=V_{SS} f=1MHz Ta=25°C 	2.2 to 5.5		10		pF

Serial I/O Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$ 1. SIO0 Serial I/O Characteristics (Note 4-1-1)

D	aramotor	Symbol	Pins	Conditions			Spec	ification		
	arameter	Symbol	/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
	Frequency	tSCK(1)	SCK0(P12)	• See Fig. 6.		2				
×	Low level pulse width	tSCKL(1)				1				
put clo	High level pulse width	tSCKH(1)			2.2 to 5.5	1			tCYC	
Ч		tSCKHA(1)		Continuous data transmission/reception mode See Fig. 6. (Note 4-1-2)		4				
	Frequency	tSCK(2)	SCK0(P12)	CMOS output selected See Fig. 6.		4/3				
ock	Low level pulse width	tSCKL(2)					1/2		tSCK	
itput clo	High level	tSCKH(2)			2.2 to 5.5		1/2		ISCK	
Out		tSCKHA(2)		 Continuous data transmission/reception mode CMOS output selected See Fig. 6. 		tSCKH(2) +2tCYC		tSCKH(2) +(10/3) tCYC	tCYC	
Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	 Must be specified with respect to rising edge of SIOCLK See fig. 6. 	2.2 to 5.5	0.03				
Da	ta hold time	thDI(1)			2.2 to 5.5	0.03				
clock	Output delay time	tdD0(1)	SO0(P10), SB0(P11),	Continuous data transmission/reception mode (Note 4-1-3)	2.2 to 5.5			(1/3)tCYC +0.05		
Input		tdD0(2)		Synchronous 8-bit mode (Note 4-1-3)	2.2 to 5.5			1tCYC +0.05	μs	
Serial output Output clock Ir		tdD0(3)		• (Note 4-1-3)	2.2 to 5.5			(1/3)tCYC +0.15		
	Input clock B Output clock Input clock	Yoo Low level pulse width High level pulse width High level pulse width Kow level pulse width High level pulse width Output delay time	Frequency tSCK(1) Low level pulse width tSCKL(1) High level pulse width tSCKH(1) High level pulse width tSCKH(1) Frequency tSCKH(2) Low level pulse width tSCKL(2) High level pulse width tSCKH(2) High level pulse width tSCKH(2) High level pulse width tSCKH(2) Data setup time tSDI(1) Data hold time thDI(1) yoo ture Output delay time tdD0(1) tdD0(2) tdD0(3)	Parameter Symbol /Remarks Frequency tSCK(1) SCK0(P12) Low level pulse width tSCKL(1) pulse width SCK0(P12) High level pulse width tSCKH(1) Frequency Frequency tSCKL(2) SCK0(P12) Low level pulse width tSCKL(2) SCK0(P12) Low level pulse width tSCKL(2) SCK0(P12) Low level pulse width tSCKL(2) SCK0(P12) Data setup time tSCKHA(2) SB0(P11), SI0(P11) Data hold time thDI(1) SO0(P10), SB0(P11), SB0(P11), yoo padel Output delay time tdD0(1) SO0(P10), SB0(P11),	Parameter Symbol /Remarks Conditions Frequency tSCK(1) SCK0(P12) • See Fig. 6. Low level pulse width tSCKL(1) • Continuous data transmission/reception mode • See Fig. 6. • Continuous data transmission/reception mode • See Fig. 6. Frequency tSCK4(2) SCK0(P12) • Continuous data transmission/reception mode • See Fig. 6. Low level pulse width tSCKL(2) SCK0(P12) • CMOS output selected • See Fig. 6. Low level pulse width tSCKH2) • Continuous data transmission/reception mode • CMOS output selected • See Fig. 6. Data setup time tsDl(1) SB0(P11), SI0(P11) • Must be specified with respect to rising edge of SIOCLK • See Fig. 6. vog proportional pulse tdD0(1) SO0(P10), SB0(P11), • Continuous data transmission/reception mode • (Note 4-1-3) vog proportional pulse tdD0(2) tdD0(2) • Continuous data transmission/reception mode • (Note 4-1-3)	Parameter Symbol /Remarks Conditions $V_{DD}[V]$ Frequency tSCK(1) SCK0(P12) *See Fig. 6. 2.2 to 5.5 Low level tSCKH(1) *SCKH(1) *Continuous data 2.2 to 5.5 pulse width tSCKH(1) *Continuous data *Continuous data *Continuous data pulse width tSCKL(2) SCK0(P12) *CMOS output selected *See Fig. 6. Low level tSCKL(2) SCK0(P12) *CMOS output selected *See Fig. 6. pulse width tSCKL(2) SCK0(P12) *Continuous data *Cansmission/reception mode *See Fig. 6. pulse width tSCKH2 SCK0(P12) *CMOS output selected *See Fig. 6. pulse width tSCKH2 SB0(P11), *Must be specified with respect to rising edge of SIOCLK 2.2 to 5.5 Data setup time thDl(1) SB0(P11), *Continuous data transmission/reception mode vopponel tdD0(1) SO(P10), *Continuous data 2.2 to 5.5 *See Fig. 6. tdD0(2) *See Fig. 6. 2.2 to 5.5	Parameter Symbol /Remarks Conditions Vpp[V] min Image: pulse width iSCK(1) SCK0(P12) • See Fig. 6. 2 1 Low level iSCKL(1) iSCK1(1) • See Fig. 6. 2.2 to 5.5 1 High level iSCKH(1) iSCK1(1) • Continuous data • Continuous data 1 2 IsckHA(1) iSCK1(2) • Continuous data • Continuous data • Continuous data 4 4 isckHA(1) iSCK1(2) • Continuous data • Continuous data 4 4/3 isckH(2) pulse width iSCK1(2) • Continuous data 2.2 to 5.5 4/3 ipulse width iscKH(2) • Continuous data • Continuous data iscK1(2) 4/3 pulse width iscKH(2) • Continuous data • Continuous data iscK1(2) 2.2 to 5.5 0.03 Data setup time isb0(1) SB0(P11), SB0(P11), • Must be specified with respect to rising edge of SIOCLK 2.2 to 5.5 0.03 Data hold time itdD0(1)	Parameter Symbol Remarks Conditions Vpp[V] min typ Frequency tSCK(1) SCK0(P12) •See Fig. 6. 2.2 to 5.5 1 1 Low level pulse width tSCKH(1) *Continuous data transmission/reception mode •See Fig. 6. •Continuous data transmission/reception mode •See Fig. 6. 2.2 to 5.5 1 1 Vise Width tSCK4(2) SCK0(P12) •Continuous data transmission/reception mode •See Fig. 6. •Continuous data transmission/reception mode •See Fig. 6. 4/3 1 Low level pulse width tSCK1(2) SCK0(P12) •Continuous data transmission/reception mode •CMOS output selected ·See Fig. 6. 2.2 to 5.5 4/3 1 Low level pulse width tSCKH(2) SCK0(P12) •Continuous data transmission/reception mode •CMOS output selected ·CMOS output selecte	Parameter Symbol /Remarks Conditions Vpp[V] min typ max Frequency tSCK(1) SCK0(P12) • See Fig. 6. 1	

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: To use serial-clock-input in continuous trans/rec mode, a time from SIORUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 6.

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

	_		Oursehal	Pins/	Conditions			Spec	ification	
	P	arameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	ĸ	Frequency	tSCK(3)	SCK1(P15)	• See Fig. 6.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.2 to 5.5	1			
clock	In	High level pulse width	tSCKH(3)				1			tCYC
Serial clock	ck	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected. See Fig. 6.		2			
	Output clock	Low level pulse width	tSCKL(4)			2.2 to 5.5	1/2			tSCK
	οu	High level pulse width	tSCKH(4)				1/2			
input	Data setup time		tsDI(2)	SB1(P14), SI1(P14)	 Must be specified with respect to rising edge of SIOCLK. See fig. 6. 		0.03			
Serial input	Da	Data hold time thDI(2)				2.2 to 5.5	0.03			
Serial output	Output delay time		tdD0(4)	SO1(P13), SB1(P14)	 Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 6. 	2.2 to 5.5			(1/3)tCYC +0.05	μs

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

Pulse Input Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Demonster	Symbol	Din s /D ann a dua	Que d'itiene		Specification			
Parameter	Symbol	Pins/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level	tPIH(1)	INT0(P70),	 Interrupt source flag can be set. 					
pulse width	tPIL(1)	INT1(P71),	Event inputs for timer 0 or 1 are					
		INT2(P72),	enabled.					
		INT4(P20 to P23),		2.2 to 5.5	1			
		INT5(P24 to P27),						
		INT6(P20),						
		INT7(P24)						tCYC
	tPIH(2)	INT3(P73) when noise filter	 Interrupt source flag can be set. 	2.2 to 5.5	2			
	tPIL(2)	time constant is 1/1.	• Event inputs for timer 0 are enabled.	2.2 10 5.5	2			
	tPIH(3)	INT3(P73) when noise filter	 Interrupt source flag can be set. 	2.2 to 5.5	64			
	tPIL(3)	time constant is 1/32	• Event inputs for timer 0 are enabled.	2.2 10 5.5	64			
	tPIH(4)	INT3(P73) when noise filter	 Interrupt source flag can be set. 	2.2 to 5.5	256			
	tPIL(4)	time constant is 1/128	• Event inputs for timer 0 are enabled.	2.2 to 5.5	256			
	tPIL(5)	RES	Resetting is enabled.	2.2 to 5.5	200			μs

AD Converter Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

5	0.1.1				Specification					
Parameter	Symbol	Pins/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit		
Resolution	N	AN0(P80) to		3.0 to 5.5		8		bit		
Absolute accuracy	ET	AN6(P86), AN8(P70),	(Note 6-1)	3.0 to 5.5			±1.5	LSB		
Conversion time	TCAD	AN9(P71), AN10(XT1), AN11(XT2)	AD conversion time=32×tCYC (when ADCR2=0) (Note 6-2)	4.5 to 5.5	11.74 (tCYC= 0.367μs)		97.92 (tCYC= 3.06μs)			
				3.0 to 5.5	23.53 (tCYC= 0.735μs)		97.92 (tCYC= 3.06μs)			
			AD conversion time=64×tCYC (when ADCR2=1) (Note 6-2)	4.5 to 5.5	15.68 (tCYC= 0.245μs)		97.92 (tCYC= 1.53μs)	μs		
				3.0 to 5.5	23.49 (tCYC= 0.367μs)		97.92 (tCYC= 1.53μs)			
Analog input voltage range	VAIN			3.0 to 5.5	V _{SS}		V _{DD}	V		
Analog port	IAINH]	VAIN=V _{DD}	3.0 to 5.5			1			
input current	IAINL		VAIN=V _{SS}	3.0 to 5.5	-1			μA		

Note 6-1: The quantization error ($\pm 1/2$ LSB) is excluded from the absolute accuracy value.

Note 6-2: The conversion time refers to the interval from the time the instruction for starting the converter is issued till the time the complete digital value corresponding to the analog input value is loaded in the required register.

Consumption Current Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Parameter	Symbol	ymbol Pins/Remarks	Conditions		Specification			
. a.a.neter	0,			V _{DD} [V]	min	typ	max	unit
Normal mode consumption current (Note 7-1)	IDDOP(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	 FmCF=12MHz ceramic oscillation mode FmX'tal=32.768kHz by crystal oscillation mode System clock set to 12MHz side 	4.5 to 5.5		9.1	18.5	
(1018 7-1)			 Internal RC oscillation stopped frequency variable RC oscillation stopped 1/1 frequency division ratio. 	2.8 to 4.5		5.3	13.5	
	IDDOP(2)		FmCF=8MHz ceramic oscillation mode FmX'tal=32.768kHz by crystal oscillation mode Syndam clock cet to 8MU to side	4.5 to 5.5		6.7	14	
	IDDOP(3)		 System clock set to 8MHz side Internal RC oscillation stopped frequency variable RC oscillation stopped 1/1 frequency division ratio. 	2.5 to 4.5		3.8	10	
	IDDOP(4)		FmCF=4MHz ceramic oscillation mode FmX'tal=32.768kHz by crystal oscillation mode Syndam clock cet to 4MUz side	4.5 to 5.5		2.7	6	mA
	IDDOP(5)		 System clock set to 4MHz side Internal RC oscillation stopped frequency variable RC oscillation stopped 1/2 frequency division ratio. 	2.2 to 4.5		1.45	3.8	
	IDDOP(6)		 FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz by crystal oscillation mode 	4.5 to 5.5		0.95	4.3	
	IDDOP(7)		 System clock set to internal RC oscillation frequency variable RC oscillation stopped 1/2 frequency division ratio. 	2.2 to 4.5		0.53	3.0	
	IDDOP(8)		 FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz by crystal oscillation mode. 	4.5 to 5.5		1.25	5.2	
	IDDOP(9)		 System clock set to 1MHz with frequency variable RC oscillation Internal RC oscillation stopped 1/2 frequency division ratio. 	2.2 to 4.5		0.67	4.2	
	IDDOP(10)		 FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz by crystal oscillation mode. 	4.5 to 5.5		38	110	
	IDDOP(11)		 System clock set to 32.768kHz side. Internal RC oscillation stopped frequency variable RC oscillation stopped 1/2 frequency division ratio. 	2.2 to 4.5		19	70	μA
HALT mode consumption current (Note 7-1)	=V _{DD}	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	 HALT mode FmCF=12MHz ceramic oscillation mode FmX'tal=32.768kHz by crystal oscillation mode 	4.5 to 5.5		3.2	7.5	
			 System clock set to 12MHz side Internal RC oscillation stopped frequency variable RC oscillation stopped 1/1 frequency division ratio. 	2.8 to 5.5		1.8	4	
	IDDHALT(2)		HALT mode FmCF=8MHz ceramic oscillation mode FmX'tal=32.768kHz by crystal oscillation mode	4.5 to 5.5		2.4	5.3	mA
	IDDHALT(3)		 System clock set to 8MHz side Internal RC oscillation stopped frequency variable RC oscillation stopped 1/1 frequency division ratio. 	2.5 to 4.5		12.5	2.8	

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors

Continued on next page.

Parameter	Symbol	Pins/Remarks	Conditions		Specification				
1 didinetei	Gymbol	T III3/ITCEIIIdIRS	Conditions	V _{DD} [V]	min	typ	max	unit	
HALT mode consumption current (Note 7-1)	IDDHALT(4)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	 HALT mode FmCF=4MHz ceramic oscillation mode FmX'tal=32.768kHz by crystal oscillation mode 	4.5 to 5.5		1	2.3		
	IDDHALT(5)		 System clock set to 4MHz side Internal RC oscillation stopped frequency variable RC oscillation stopped 1/2 frequency division ratio. 	2.2 to 4.5		0.5	1.3		
	IDDHALT(6)		HALT mode FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz by crystal oscillation mode	4.5 to 5.5		0.33	0.9	mA	
	IDDHALT(7)		 System clock set to internal RC oscillation frequency variable RC oscillation stopped 1/2 frequency division ratio. 	2.2 to 4.5		0.17	0.7		
	IDDHALT(8)		 HALT mode FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz by crystal oscillation mode. 	4.5 to 5.5		1	3.8		
	IDDHALT(9)		 System clock set to 1MHz with frequency variable RC oscillation Internal RC oscillation stopped 1/2 frequency division ratio. 	2.2 to 4.5		0.5	2.7		
	IDDHALT(10)		HALT mode FmCF=0Hz (oscillation stopped) FmX'tal=32.768kHz by crystal oscillation mode.	4.5 to 5.5		18	70		
	IDDHALT(11)		 System clock set to 32.768kHz side. Internal RC oscillation stopped frequency variable RC oscillation stopped 1/2 frequency division ratio. 			5	63	μA	
HOLD mode	IDDHOLD(1)	V _{DD} 1	HOLD mode	4.5 to 5.5		0.03	18		
consumption current	IDDHOLD(2)		 CF1=V_{DD} or open (External clock mode) 	2.2 to 4.5		0.01	14		
Timer HOLD mode	IDDHOLD(3)		Timer HOLD mode CF1=V _{DD} or open (External clock mode)	4.5 to 5.5		16	63		
consumption current	IDDHOLD(4)			2.2 to 4.5		3.5	50		

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors

F-ROM Programming Characteristics at $Ta = +10^{\circ}C$ to $+55^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Parameter	Symbol	Dine/Demort/e	Conditions		Specification				
	Symbol	Pins/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
Onboard programming current	IDDFW(1)	V _{DD} 1	Without CPU current	2.7 to 5.5		5	10	mA	
Programming	tFW(1)		• Erasing	2.7 to 5.5		20	30	ms	
time	tFW(2)	W(2) • programming		2.7 to 5.5		40	60	μs	

UART (Full Duplex) Operating Conditions at Ta = -40 °C to +85 °C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0$ V

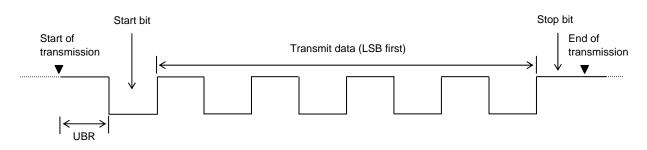
	Deremeter	Or weath and	Pins/Remarks	Que distance		Specification			
	Parameter	Symbol	Pins/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	Transfer rate	UBR	P32 (UTX1),						
			P33 (URX1),		2.5 to 5.5	16/3		8192/3	tCYC
			P34 (UTX2),		2.5 10 5.5	10/3		0192/3	
L			P35 (URX2)						

Data length : 7, 8, and 9 bits (LSB first)

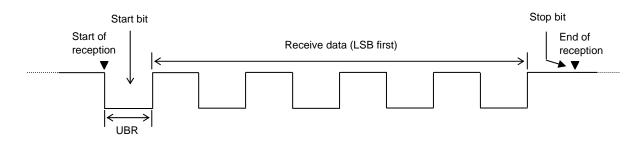
Stop bits : 1-bit (2-bit in continuous data transmission)

Parity bits : None

Example of Continuous 8-bit Data Transmission Mode Processing (First Transmit Data = 55H)



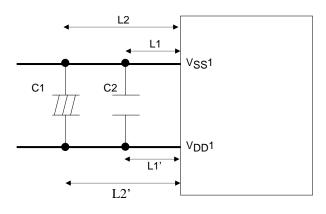
Example of Continuous 8-bit Data Reception Mode Processing (First Receive Data = 55H)



VDD1, VSS1 Terminal Condition

It is necessary to place capacitors between V_{DD1} and V_{SS1} as describe below.

- Place capacitors as close to VDD1 and VSS1 as possible.
- Place capacitors so that the length of each terminal to the each leg of the capacitor be equal (L1 = L1', L2 = L2').
- Place high capacitance capacitor C1 and low capacitance capacitor C2 in parallel.
- \bullet Capacitance of C2 must be more than 0.1 $\mu F.$
- Use thicker pattern for VDD1 and VSS1.



Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Nominal Vendor			Circuit Constant			Operating Voltage	Oscillation Stabilization Time		Durali		
Frequency	Name	Oscillator Name	C1	C2	Rf1	Rd1	Range	typ	max	Remarks	
			[pF]	[pF]	[Ω]	[Ω]	[V]	[ms]	[ms]		
12MHz		CSTCE12M0G52-R0	(10)	(10)	Open	470	2.6 to 5.5	0.03	0.5	Internal C1,C2	
			CSTCE10M0G52-R0	(10)	(10)	Open	470	2.4 to 5.5	0.03	0.5	Internal C1,C2
10MHz					CSTLS10M0G53-B0	(15)	(15)	Open	680	2.6 to 5.5	0.03
01411-	MURATA	CSTCE8M00G52-R0	(10)	(10)	Open	680	2.3 to 5.5	0.03	0.5	Internal C1,C2	
8MHz		CSTLS8M00G53-B0	(15)	(15)	Open	1k	2.5 to 5.5	0.03	0.5	Internal C1,C2	
45411-		CSTCR4M00G53-R0	(15)	(15)	Open	1.5k	2.2 to 5.5	0.03	0.5	Internal C1,C2	
4MHz		CSTLS4M00G53-B0	(15)	(15)	Open	1.5k	2.2 to 5.5	0.03	0.5	Internal C1,C2	

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after V_{DD} goes above the operating voltage lower limit (see Fig. 4).

Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

	uble 2 Characteristics of a Sumple Subsystem Clock Osemator Chean with a Crystar Osemator											
Nominal Vendor	Vendor	On sillaton Nama		Circuit C	Constant		Operating Voltage	Oscillation Stabilization Time		Demostro		
Frequency	Name	Oscillator Name	C3	C4	Rf2	Rd2	Range [V]	typ	max	Remarks		
			[pF]	[pF]	[Ω]	[Ω]	[v]	[s]	[s]			
32.768kHz	EPSON TOYOCOM	MC-306	18	18	Open	560k	2.2 to 5.5	1.2	3.0	Applicable CL value=12.5pF		

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after the instruction for starting the subclock oscillation circuit is executed and to the time interval that is required for the oscillation to get stabilized after the HOLD mode is reset (see Figure. 4).

Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

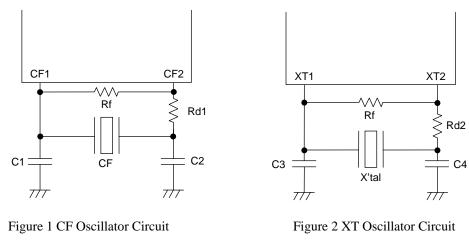
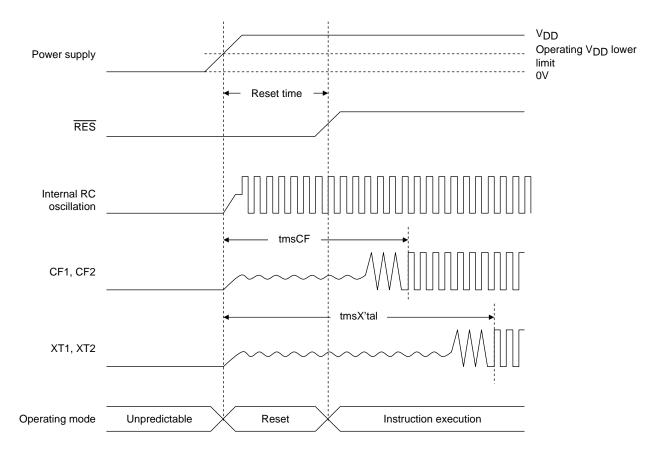
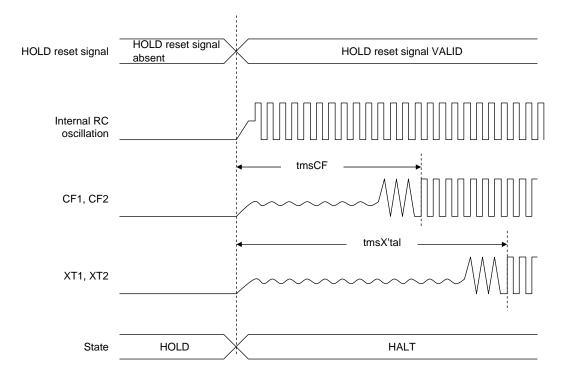




Figure 3 AC Timing Measurement Point



Reset Time and Oscillation Stabilization Time



HOLD Release Signal and Oscillation Stabilization Time

Figure 4 Oscillation Stabilization Times

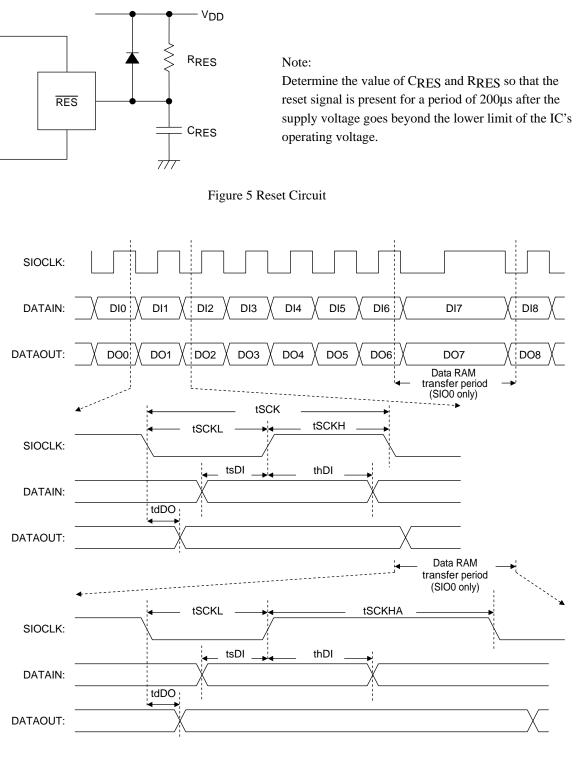


Figure 6 Serial I/O Waveforms

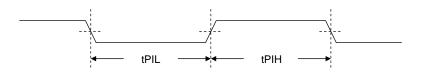


Figure 7 Pulse Input Timing Signal Waveform

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